

QLSP23BA V1.0 (0402 Blue LED)





#### **Product Outline:**

SMD LED lamps from Quelighting are available in miniature sizes and special configurations for automated PC board assembly and space-sensitive applications. These SMD LED lamps are suitable for use in a wide variety of electronic equipment, including cordless and cellular phones, notebook computers, network systems, home appliances, and indoor signboard applications.

#### Features:

- Compatible with automatic placement equipment.
- RoHS compliant
- Package Dimension = 1.0mmX0.55mmX0.48mm (0402 package)
- Compatible with infrared and vapor phase reflow solder process.
- Custom Bin available upon special request

### **Application:**

- Backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Flat backlight for LCD, switch and symbol.
- General use.
- Microdisplays

### **Compliance and Certification:**

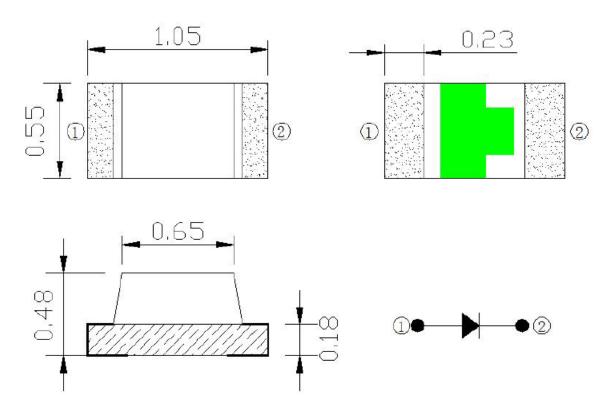






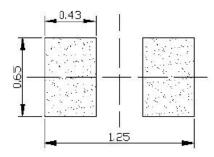


# Mechanical Property: (Dimension)



- \* All dimensions are in millimeters,
- \* Tolerances are ± 0.10mm.

### **Recommended Solder footprint:**



- \* All dimensions are in millimeters.
- \* Reflow soldering must not be performed more than twice.





# **Characteristics**

### ■ Absolute Maximum Ratings

(Ta=25°C)

Parameter	Symbol	Rating	Unit
Reverse Voltage	$V_{R}$	5	V
DC Forward Current	lf	25	mA
Pulse Forward Current (Duty 1/10 @1KHz)	<b> </b> FP	60	mA
Total Power Dissipation	Pd	75	mW
Electrostatic Discharge (HBM)	ESD	2000	V
Storage Temperature	Tstg	-40 ~ 85	${\mathbb C}$
Operation Temperature	Topr	-40 ~ 85	$^{\circ}$
Soldering Temperature	Tsol	260 < 10 sec	°C

<sup>(1)</sup> Proper current rating must be observed to maintain junction temperature below maximum at all time

### ■ Electrical / Optical Characteristic

(Ta=25 oC)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Luminous Intensity	lv	28.5		71.5	mcd	
Peak Wavelength	λр		468		nm	
Dominant Wavelength	λd	460		470	nm	I==5mA
Forward Voltage	Vf	2.5		2.9	V	
View Angle	θ		120		deg	

- (1). Tolerance of Luminous Intensity: ±11%
- (2). Tolerance of Dominant Wavelength ±1nm
- (3). Tolerance of measurement: VF=+/- 0.1V





# ■ Groups

Forward Voltage (V<sub>F</sub>) Bin:

VF Rank (V)				Condition
Color	Code name	Low	High	unit
	W	2.5	2.6	
	Х	2.6	2.7	
Blue	Υ	2.7	2.8	ΙΓ <i>Ε</i> το Λ
	Z	2.8	2.9	IF=5mA

**Luminous Intensity Bin:** 

	Rank (mcd)			
Color	Code name	Low	High	Unit
Blue	N	28.5	45	IF=5mA
	Р	45	71.5	

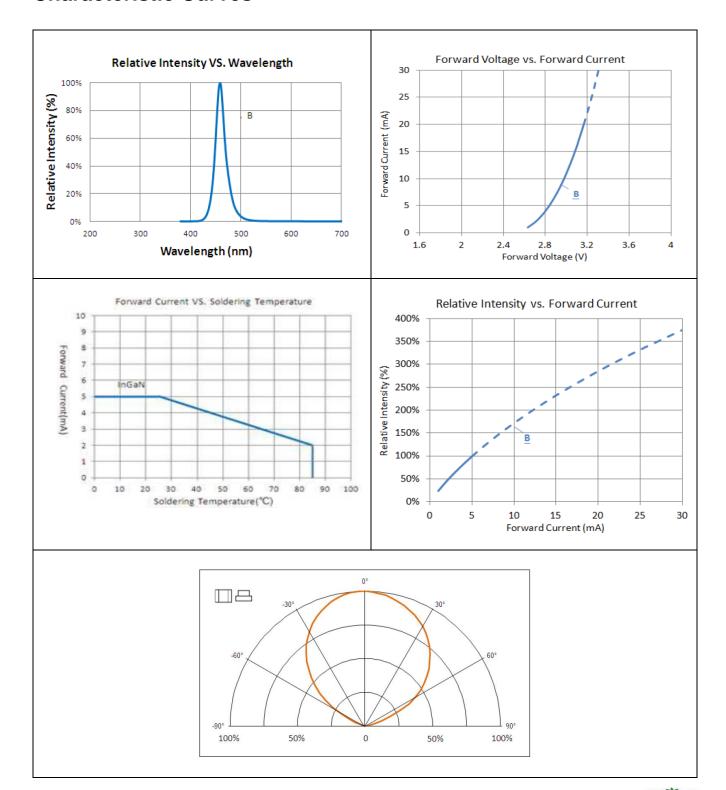
**Dominant Wavelength Bin:** 

Rank (nm)				Condition
Color	Code name	Low	High	Unit
	DC	460	465	
Blue	DD	465	470	IF=5mA





### **Characteristic Curves**





# ■ Reliability test:

No	Item	Condition	Time/Cycle	Sample size
1	Steady State Operating Life of Room Temperature	25 <sup>°</sup> C Operating	1000 Hrs	20 pcs
2	Steady State Operating Life of Low Temperature -40°C	-40°C Operating	1000 Hrs	20 pcs
3	Steady State Operating Life of Low Temperature $60^{\circ}\!\mathbb{C}$	60℃ Operating	1000 Hrs	20 pcs
4	Steady State Operating Life of Low Temperature $85^{\circ}\!\mathbb{C}$	85℃ Operating	1000 Hrs	20 pcs
5	Low temperature storage -40°C	-40°C Storage	1000 Hrs	20 pcs
6	High temperature storage 100°C	100°C Storage	1000 Hrs	20 pcs
7	Steady State Operating Life of High Humidity Heat 60°C 90%	60°C/90% Operating	1000 Hrs	20 pcs
8	Steady State Pulse Operating Life Condition	25°C 10Hz duty=1/10 Operating	200 Cycle	20 pcs
9	Resistance to soldering heat on PCB (JEDEC MSL3)	pre-store@60°ℂ, 60%RH for 52hrs Tsld max.=260 10sec	3 Times	20 pcs
10	Heat Cycle Test (JEDEC MRC)	25℃ ~65℃ ~-10℃ , 90%RH, 24hr/1cycle	10 Cycle	20 pcs
11	Thermal shock	-40°C / 20minr~ 5minr~100°C /20min	300 Cycle	20 pcs

■ Judgment Criteria:

Item	Symbol	Test Condition	Judgment Criteria
Forward Voltage	Vf	15.50	△Vf< 10%
Luminous Flux	lv	IF=50 mA	∆lv< 30%

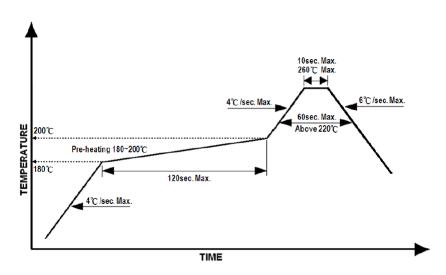




#### **Solder Profile:**

- -The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):
- 1. Operating temp.: Above 220 °C ,60 sec.
- 2. Peak temp.:260 °C Max.,10sec Max.
- 3. Reflow soldering should not be done more than two times.
- 4. Never attempt next process until the component is cooled down to room temperature after reflow
- 5. The recommended reflow soldering profile (measured on the surface of the LED terminal) is as following:

#### Lead-free Solder Profile

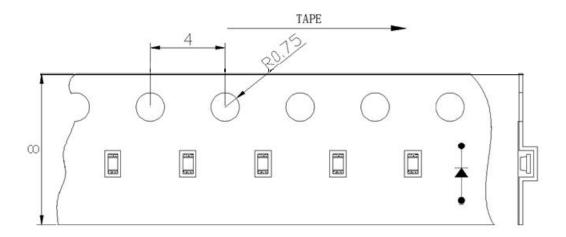


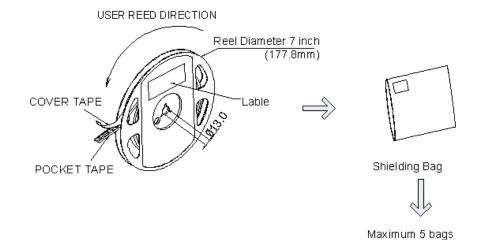
#### Reworking

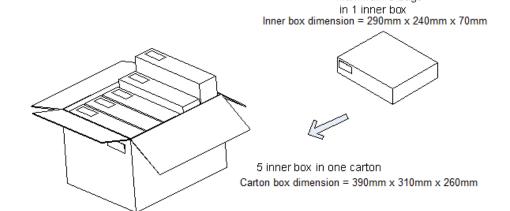
- Rework should be completed within 5 seconds under 260°C.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.



# **Taping & Packing:**











# Labeling

Uantity: XXXX

Quelighting P/N: XXXXXX

Lot number: XXXXX

Iv Bin: XX

Color Bin: XX

Vf Bin: XX

Date Code: XXXX

QueLighting

## **Ordering Information:**

Part #	Multiple Quantities	Quantity per Reel
QLSP23BA		3000 pcs





**Revision History:** 

Revision Date:	Changes:	Version #:
01-2023	Initial release	1.0

